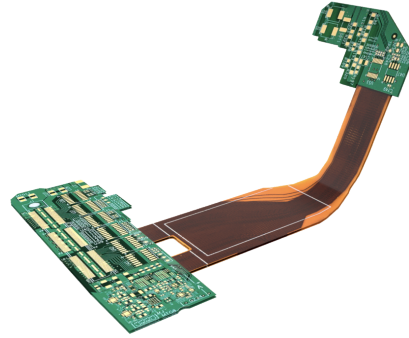


The Importance of Communication



Features	Standard	Advanced
Number of Layers	1 - 16 Layers	26 Layers
Base Material	FR-4, Polyimide (PI)	PET, BT
Minimum Board Thickness	0.40mm	0.35mm
Minimum Size	100mm x 100mm	15mm x 15mm
Maximum Size	610mm x 460mm	800mm x 600mm
Surface Finishing	Electro-less Nickel Immersion Gold (ENIG) Electrolytic Nickel and Gold Immersion Tin Organic Solder-ability Preservative (OSP)	
Cover Material	Liquid Photo Imaging (LPI); Polyimide (PI)	
Profiling	Routing, Laser Cutting, Punching	